



Material Content Data Sheet



Sales Product Name	BTS133TC	Issued	01. May 2021
MA#	MA000701082		
Package	PG-TO263-3-2	Weight*	1539.70 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	5.075	0.33	0.33	3296	3296
chip_2	inorganic material	silicon	7440-21-3	0.454	0.03	0.03	295	295
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	iron	7439-89-6	0.304	0.02		198	
	non noble metal	copper	7440-50-8	304.026	19.75	19.78	197458	197715
wire	non noble metal	aluminium	7429-90-5	1.746	0.11	0.11	1134	1134
encapsulation	organic material	carbon black	1333-86-4	7.346	0.48		4771	
	inorganic material	antimonytrioxide	1309-64-4	15.360	1.00		9976	
	plastics	brominated resin	-	17.364	1.13		11278	
	plastics	epoxy resin	-	126.890	8.24		82413	
	inorganic material	silicondioxide	60676-86-0	500.883	32.53	43.38	325313	433751
leadfinish	non noble metal	tin	7440-31-5	9.657	0.63	0.63	6272	6272
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	148	149
solder	non noble metal	tin	7440-31-5	0.029			19	
	noble metal	silver	7440-22-4	0.036			24	
	non noble metal	lead	7439-92-1	1.392	0.09	0.09	904	947
glue	plastics	Polyimide	26023-21-2	0.432	0.03	0.03	281	281
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		107	
	non noble metal	iron	7439-89-6	0.548	0.04		356	
	non noble metal	copper	7440-50-8	547.666	35.56	35.61	355697	356160
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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